

# H48-2K

## Thermal Conductive Pad



### Features

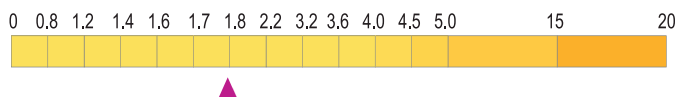
Non-reinforcement carrier  
Low contact thermal impedance  
Non-Oil Bleed  
High dielectric breakdown voltage

### Applications

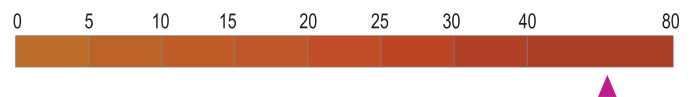
Electronic components: IC / CPU / MOS  
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /  
Wireless Hub etc....  
DDR II Module / DVD Applications / Hand-Set applications etc...

### Properties

Thermal Conductivity: 1.8 W/m.k  
(W / m.k - Z Axis)



Hardeness: 60 (Shore A)  
(Shore A)



Property	H48-2K	Unit	Test Method
Thickness (+/- 10%)	0.1/0.2/0.3	mm	-
Color	Dark Red	-	Visual
Construction	Silicone based with ceramic fillers (non-silicone oil)	-	-
Opt.Temp. Range	-45 to 200	°C	-
Density	2.1	g/cm <sup>3</sup>	ASTM D792
Thermal Conductivity	1.8	W/m.k	ASTM D5470
Hardness Shore A	60	-	ASTM D2240
Thermal impedance			ASTM D5470
10psi	0.21/0.37/0.57	K- in <sup>2</sup> /W	-
50psi	0.20/0.33/0.51	K- in <sup>2</sup> /W	-
100psi	0.17/0.31/0.46	K- in <sup>2</sup> /W	-
Percent deflection			ASTM D575
10psi	2	%	-
50psi	5	%	-
100psi	11	%	-
Breakdown voltage	1.2 / 2.5 / 3.5	kV	ASTM D149
TML	< 0.5%	%	ASTM E595
Tensile strength	200	Psi	ASTM D412
Elongation	50	%	ASTM D412
UL flammability	V-0	-	UL 94

Need samples?

Available to apply adhesive

Pre-cut different shape



X y z  
H48-2K - 15 - 20 - 0.2 - 1A, 20 4  
1 2 3

1. Choose the P/N
2. Fill into size: x,y,z
3. Apply the adhesive or not? 0=none, 1A= one side, 2A= two sides
4. Fill the quantity you need